

11-08-2005

FORM PTO-1595

REC

(Rev. 10/02)

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

Docket No.: 074128-0015

103115991

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):

Hiroyuki UCHIYAMA

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: October 19, 2005

2. Name and address of receiving party(ies):

Name: Elpida Memory, Inc.

Address: 2-1, Yaesu 2-chome, Chuo-ku

Tokyo, Japan

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is: October 19, 2005

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL &amp; EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

500417

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Stephen A. Becker, P.C., Registration No. 26,527

November 2, 2005

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet:

2

OMB No. 0651-0027 (exp. 6/30/2005)

11/07/2005 BYRME 00000055 500417 11264092

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40.00 DA

PATENT  
REEL: 017172 FRAME: 0586

(SAB)

Docket No.: \_\_\_\_\_

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

Hiroyuki UCHIYAMA

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

Elpida Memory, Inc., a Japanese Corporation, having a place of business at 2-1, Yaesu 2-chome,  
Chuo-ku, Tokyo, Japan

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME

(a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Serial No. \_\_\_\_\_; or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR

DATE SIGNED

Hiroyuki Uchiyama  
Name: Hiroyuki UCHIYAMA



19/10/2005

ELPO 4004 US

RECORDED: 11/02/2005

PATENT  
REEL: 017172 FRAME: 0587